

# *Vapor Phase – Soldering System*

*Mini-Condens-IT  
Jumbo-Condens-IT*



- *Tabletop - Toploader*
- *Suitable for BGAs, Stacked Packages*
- *Process chamber with viewing window*
- *Oxygen-free soldering*
- *Homogeneous temperature transfer to whole assembly*
- *No component overheating*

## Condens IT

The IMDES CONDENS - IT is designed for reflow soldering of printed circuit boards on a smaller scale, i.e. for single pieces, small quantities and small series.

It was especially designed for the development of prototypes and the processing of BGAs and LGAs.

Due to its small footprint, it is quickly ready for use and at the same time guarantees highest soldering quality.

### Technical data

	Mini	Jumbo
<b>Permissible voltage:</b>	220-240 Volt / 50-60 Hz	220-240 Volt / 50-60 Hz
<b>Max. Power:</b>	1000 Watt (approx. 5 A)	1500 Watt (approx. 6 A)
<b>Dimension:</b>	400 x 315 x 305 mm (LxWxH)	605 x 385 x 450 mm (LxWxH)
<b>Max. Soldering material size:</b>	240 x 170 x 20 mm (LxWxH)	430 x 230 x 20 mm (LxWxH)
<b>Standard cycle time:</b>	10 minutes	15-20 minutes
<b>Soldering time:</b>	Approx. 60-90 seconds	Approx. 60-90 seconds
<b>Process temperature:</b>	210 – 240 °C	210 – 240 °C
<b>Weight:</b>	6 kg	12 kg
<b>Cooling:</b>	Forced air cooling	Forced air cooling
<b>Operation resources:</b>	Galden with max. 240 °C boiling temp.	Galden with max. 240 °C boiling temp.
<b>Capacity:</b>	Approx. 450-500 ml Galden	Approx. 600 ml Galden

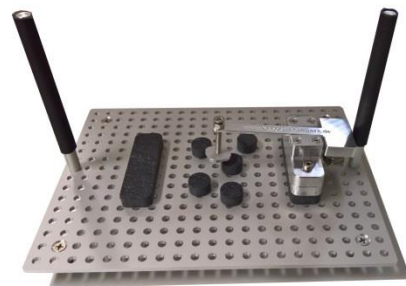
Advantages of reflow condensation soldering:

- Vapor is directly connected to the process liquid
- Vapor temperature is equal to boiling temperature (of the evaporated process liquid)
- No oxidation during soldering (no protective gas needed)
- Simple and stable process
- Process limits are defined only by physical laws
- Simple and manageable systems engineering

### Desoldering

With the vapour phase Condes-IT, not only component soldering but also multipole SMDs or BGAs can be desoldered in a process-safe and gentle manner.

The desoldering device works like a seesaw. On one side, the component to be desoldered is fixed by a double-sided heat-resistant adhesive tape. Then the assembly is heated with the desoldering device in the vapor phase. The weight on the other side of the seesaw releases the component as soon as the solder paste has reached the melting point.



### Prices: status 2020

Condens IT Mini	1,500.00 EURO*
Condens IT Jumbo	2,200.00 EURO*
Desoldering device	415.00 EURO*

\*plus VAT and other taxes and duties levied in the country of the consignee